IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved uninternational and Pan-American copyright conventions.			nder both					within the manufactur level materials for w				
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
uppliei	r Information													
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
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ontact N	lame	Title - Contact			F	Phone - Contact*				Email - Contact*				
?roduct-I	Env-Stewards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*	Title - Representative			F	Phone - Representative*				Email - Representative*				
roduct-I	Env-Stewards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version	N	Manufacturing Site		Weight*	UOM	Unit Type	
		FSFR2100XS High Pwr FPS for I		НВ		2023-06-08	СРА		:	1049.548	mg	Each		
lanufa	cturing Process Inform		Terminal Base	Alloy	-STD-020 MS	I. Doting	Dools Droo	ass Pady 7	Comporatur	e Max Time at Peak	Tomporat	ura Numba	er of Reflow Cyc	olos
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omments	,													
or more	information regarding materia	al composition	nlease refer t	n nage 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its keloardin shall encompass all such components. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and/Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	9.87	mg	Supplier	Silicon (Si)	7440-21-3		9.87	mg
Die Attach	2.18	mg	Supplier	Silver (Ag)	7440-22-4		0.0327	mg
			A	Lead (Pb)	7439-92-1	7a	2.0383	mg
			Supplier	Tin (Sn)	7440-31-5		0.109	mg
Lead Frame	339.343		Supplier	Zinc (Zn)	7440-66-6		0.407	mg
			Supplier	Iron (Fe)	7439-89-6		7.805	mg
			Supplier	Copper (Cu)	7440-50-8		331.0291	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1019	mg
Mold Compound-Black	693.0			Epoxy resin	proprietary data		41.58	mg
			Supplier	Phenolic Resin	Proprietary Data		41.58	mg
			Supplier	Carbon Black (C)	1333-86-4		3.465	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		589.05	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		17.325	mg
Plating	4.92	mg	Supplier	Tin (Sn)	7440-31-5		4.92	mg
Wire Bond - Cu	0.235	mg	Supplier	Copper (Cu)	7440-50-8		0.235	mg